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## 5-V Low Drop Fixed Voltage Regulator

TLE 4275



### Features

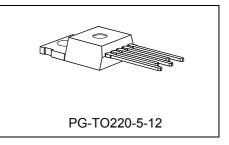
- Output voltage 5 V  $\pm$  2%
- Very low current consumption
- Power-on and undervoltage reset
- Reset low down to V<sub>Q</sub> = 1 V
- Very low-drop voltage
- Short-circuit-proof
- Reverse polarity proof
- Suitable for use in automotive electronics
- ESD protection > 4 kV
- Green Product (RoHS compliant) version of TLE 4275
- AEC qualified

### **Functional Description**

The TLE 4275 is a monolithic integrated low-drop voltage regulator in a 5-pin TO-package. An input voltage up to 45 V is regulated to  $V_{Q,nom} = 5.0$  V. The IC is able to drive loads up to 450 mA and is short-circuit proof. At overtemperature the TLE 4275 is turned off by the incorporated temperature protection. A reset signal is generated for an output voltage  $V_{Q,rt}$  of typ. 4.65 V. The delay time can be programmed by the external delay capacitor.

PG-TO220-5-11
PG-TO252-11





Туре	Package
TLE 4275	PG-TO220-5-11 (RoHS compliant)
TLE 4275 D	PG-TO252-5-11 (RoHS compliant)
TLE 4275 G	PG-TO263-5-1 (RoHS compliant)
TLE 4275 S	PG-TO220-5-12 (RoHS compliant)



### **Dimensioning Information on External Components**

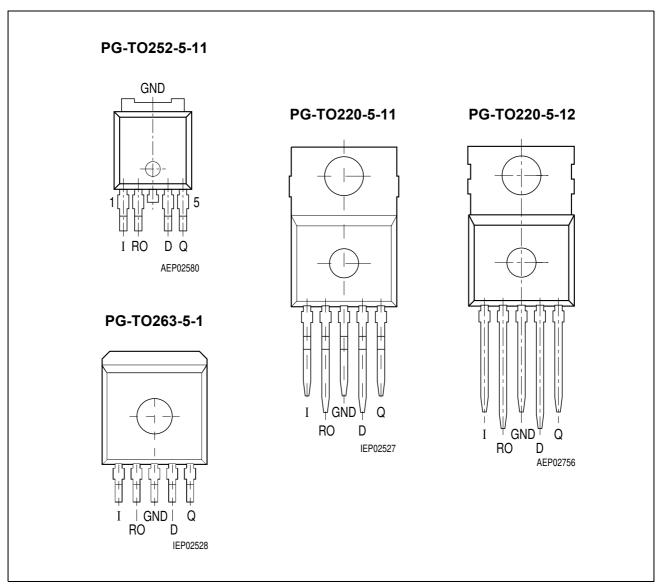
The input capacitor  $C_{\rm I}$  is necessary for compensation of line influences. Using a resistor of approx. 1  $\Omega$  in series with  $C_{\rm I}$ , the oscillating of input inductivity and input capacitance can be damped. The output capacitor  $C_{\rm Q}$  is necessary for the stability of the regulation circuit. Stability is guaranteed at values  $C_{\rm Q} \ge 22 \ \mu\text{F}$  and an ESR of  $\le 5 \ \Omega$  within the operating temperature range.

### **Circuit Description**

The control amplifier compares a reference voltage to a voltage that is proportional to the output voltage and drives the base of the series transistor via a buffer. Saturation control as a function of the load current prevents any oversaturation of the power element. The IC also incorporates a number of internal circuits for protection against:

- Overload
- Overtemperature
- Reverse polarity





## Figure 1 Pin Configuration (top view)

Pin No.	Symbol	Function
1	I	Input; block to ground directly at the IC by a ceramic capacitor.
2	RO	Reset Output; open collector output
3	GND	Ground; Pin 3 internally connected to heatsink
4	D	Reset Delay; connect capacitor to GND for setting delay time
5	Q	<b>Output;</b> block to ground with a $\ge 22 \ \mu$ F capacitor, ESR < 5 Ω at 10 kHz.



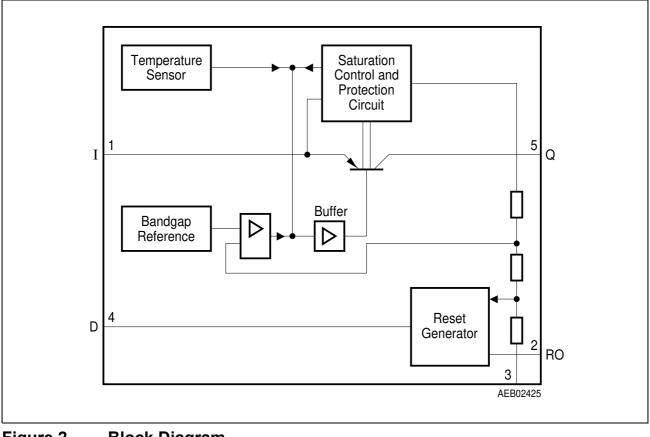


Figure 2 **Block Diagram** 



Parameter	Symbol	Lim	it Values	Unit	<b>Test Condition</b>	
		Min. Max.				
Input		•				
Voltage	V <sub>1</sub>	-42	45	V	-	
Current	I	-	-	_	Internally limite	
Output		·				
Voltage	V <sub>Q</sub>	-1.0	16	V	-	
Current	IQ	-	_	_	Internally limited	
Reset Output						
Voltage	V <sub>RO</sub>	-0.3	25	V	-	
Current	I <sub>RO</sub>	- 5	5	mA	-	
Reset Delay						
Voltage	V <sub>D</sub>	-0.3	7	V	-	
Current	ID	-2	2	mA	-	
Temperature						
Junction temperature	Tj	-40	150	°C	-	
Storage temperature	$T_{\rm stg}$	-50	150	°C	-	

### Table 2Absolute Maximum Ratings

Note: Maximum ratings are absolute ratings; exceeding any one of these values may cause irreversible damage to the integrated circuit.

### Table 3Operating Range

Parameter	Symbol	Lim	it Values	Unit	Remarks
		Min.	Max.		
Input voltage	$V_1$	5.5	42	V	-
Junction temperature	Tj	-40	150	°C	-
Thermal Resistance			·		
Junction case	$R_{ m thjc}$	_	4	K/W	_
Junction ambient	$R_{\mathrm{thj-a}}$	-	53	K/W	TO263 <sup>1)</sup>
Junction ambient	R <sub>thj-a</sub>	_	78	K/W	TO252 <sup>1)</sup>
Junction ambient	R <sub>thj-a</sub>	_	65	K/W	TO220

1) Worst case, regarding peak temperature; zero airflow; mounted on a PCB FR4,  $80 \times 80 \times 1.5 \text{ mm}^3$ , heat sink area 300 mm<sup>2</sup>



### Table 4Characteristics

 $V_{\rm I}$  = 13.5 V; -40 °C <  $T_{\rm j}$  < 150 °C (unless otherwise specified)

Parameter	Symbol	Limit Values			Unit	Measuring			
		Min.	Тур.	Max.		Condition			
Output									
Output voltage	V <sub>Q</sub>	4.9	5.0	5.1	V				
Output voltage	V <sub>Q</sub>	4.9	5.0	5.1	V	$5 \text{ mA} < I_Q < 200 \text{ mA}$ $6 \text{ V} < V_1 < 40 \text{ V}$			
Output current limitation <sup>1)</sup>	I <sub>Q</sub>	450	700	-	mA	_			
$\overline{\text{Current consumption;}} \\ I_{q} = I_{l} - I_{Q}$	Iq	_	150	200	μA	$I_Q$ = 1 mA; $T_j$ = 25 °C			
$\overline{\text{Current consumption;}} \\ I_{q} = I_{l} - I_{Q}$	Iq	_	150	220	μA	$I_{\rm Q}$ = 1 mA; $T_{\rm j}$ $\leq$ 85 °C			
$\overline{\text{Current consumption;}} \\ I_{q} = I_{l} - I_{Q}$	Iq	_	5	10	mA	I <sub>Q</sub> = 250 mA			
$\overline{\text{Current consumption;}} \\ I_{q} = I_{l} - I_{Q}$	Iq	_	12	22	mA	I <sub>Q</sub> = 400 mA			
Drop voltage <sup>1)</sup>	V <sub>dr</sub>	-	250	500	mV	$I_{\rm Q}$ = 300 mA; $V_{\rm dr}$ = $V_{\rm I}$ - $V_{\rm Q}$			
Load regulation	$\Delta V_{Q}$	-	15	30	mV	$I_{\rm Q}$ = 5 mA to 400 mA			
Line regulation	$\Delta V_{Q}$	-15	5	15	mV	$\Delta V_{\rm l}$ = 8 V to 32 V $I_{\rm Q}$ = 5 mA			
Power supply ripple rejection	PSRR	-	60	-	dB	$f_{\rm r}$ = 100 Hz; $V_{\rm r}$ = 0.5 Vpp			
Temperature output voltage drift	$dV_Q/dT$	-	0.5	-	mV/K	-			



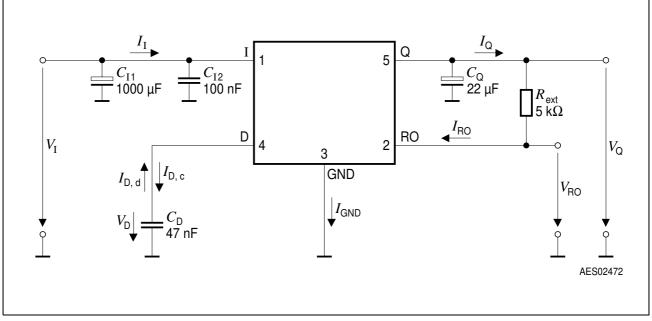
### Table 4Characteristics (cont'd)

# $V_{\rm I}$ = 13.5 V; -40 °C < $T_{\rm j}$ < 150 °C (unless otherwise specified)

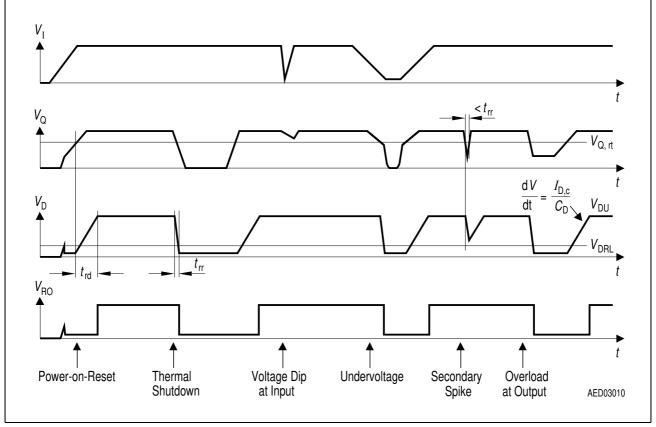
Parameter	Symbol	Limit Values			Unit	Measuring
		Min.	Тур.	Max.		Condition
Reset Timing D and Ou	tput RO					
Reset switching threshold	$V_{\rm Q,rt}$	4.5	4.65	4.8	V	-
Reset output low voltage	V <sub>ROL</sub>	_	0.2	0.4	V	$R_{\text{ext}} \ge 5 \text{ k}\Omega;$ $V_{\text{Q}} > 1 \text{ V}$
teset output leakage urrent	I <sub>ROH</sub>	-	0	10	μA	V <sub>ROH</sub> = 5 V
Reset charging current	I <sub>D,c</sub>	3.0	5.5	9.0	μA	<i>V</i> <sub>D</sub> = 1 V
Jpper timing threshold	$V_{DU}$	1.5	1.8	2.2	V	-
ower timing threshold	$V_{DRL}$	0.2	0.4	0.7	V	-
Reset delay time	t <sub>rd</sub>	10	16	22	ms	C <sub>D</sub> = 47 nF
Reset reaction time	t <sub>rr</sub>	_	0.5	2	μs	C <sub>D</sub> = 47 nF

1) Measured when the output voltage  $V_{\rm Q}$  has dropped 100 mV from the nominal value obtained at  $V_{\rm I}$  = 13.5 V.





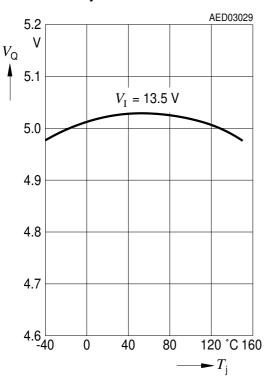




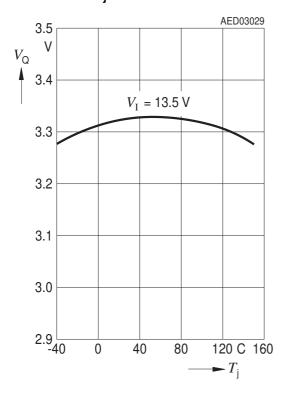




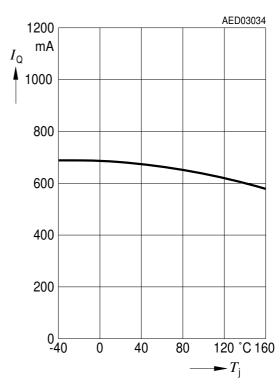
Output Voltage  $V_{Q}$  versus Temperature  $T_{i}$ 



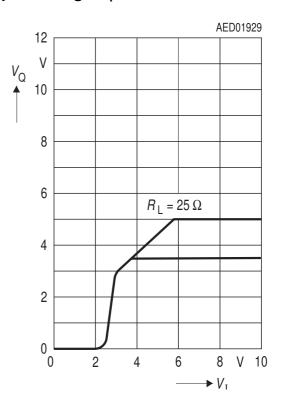
Output Voltage  $V_{\rm Q}$  versus Temperature  $T_{\rm i}$ 



Output Current  $I_{\rm Q}$  versus Temperature  $T_{\rm i}$ 

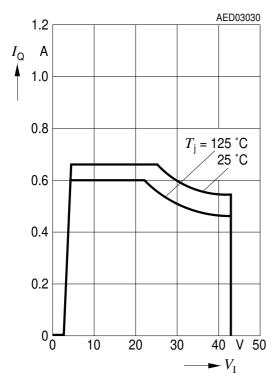


### Output Voltage $V_{Q}$ versus Input Voltage $V_{I}$

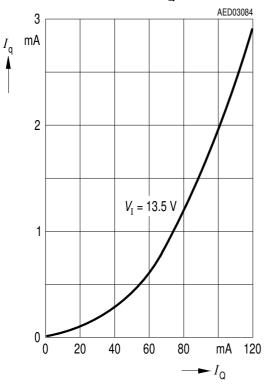


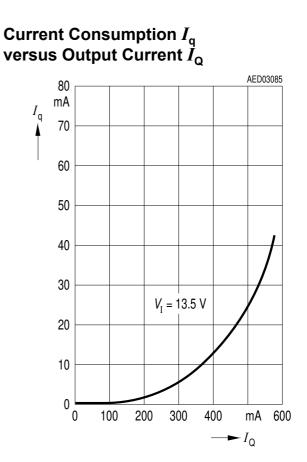


Output Current  $I_{\rm Q}$  versus Input Voltage  $V_{\rm I}$ 

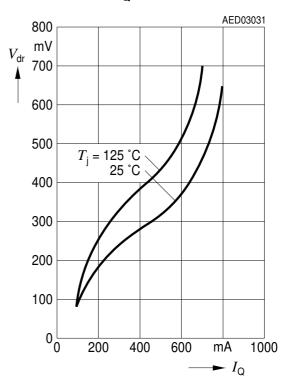


# Current Consumption $I_q$ versus Output Current $I_o$



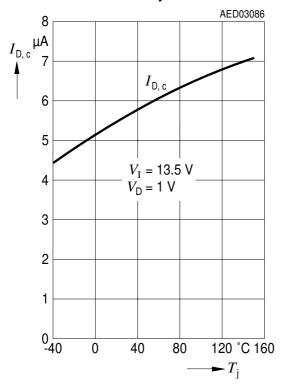


### Drop Voltage $V_{\rm dr}$ versus Output Current $I_{\rm O}$

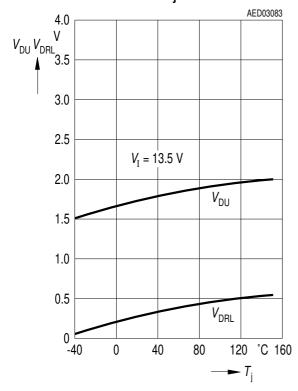




## Charge Current $I_{\rm D,c}$ versus Temperature $T_{\rm j}$

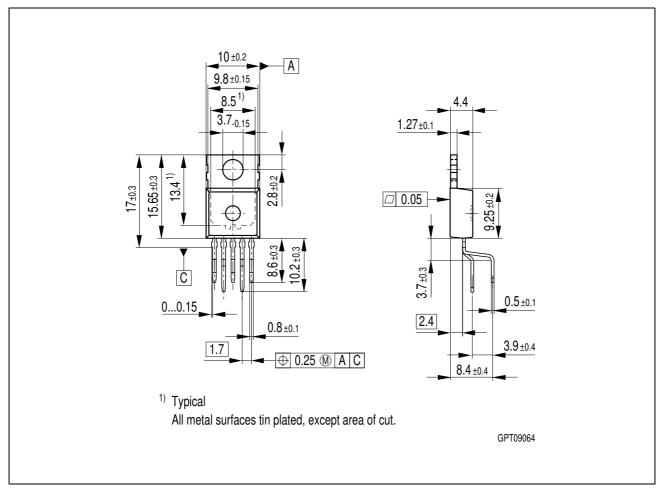


Delay Switching Threshold  $V_{\rm DU,}$   $V_{\rm DRL}$  versus Temperature  $T_{\rm j}$ 





### **Package Outlines**





### **Green Product (RoHS compliant)**

To meet the world-wide customer requirements for environmentally friendly products and to be compliant with government regulations the device is available as a green product. Green products are RoHS-Compliant (i.e Pb-free finish on leads and suitable for Pb-free soldering according to IPC/JEDEC J-STD-020).

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SMD = Surface Mounted Device



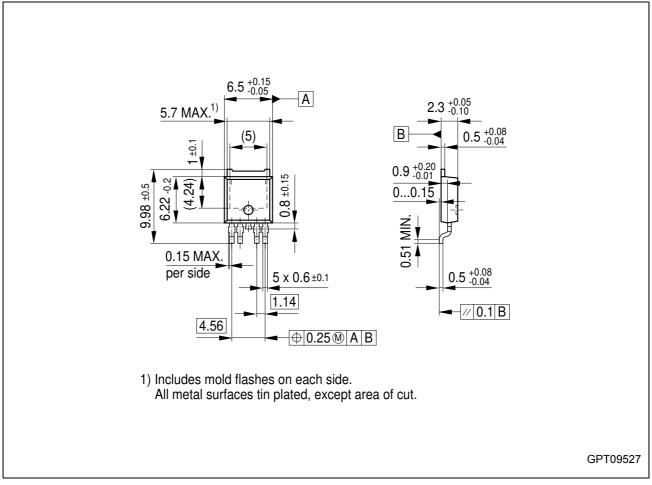


Figure 6 PG-TO252-5-11 (Plastic Transistor Single Outline)

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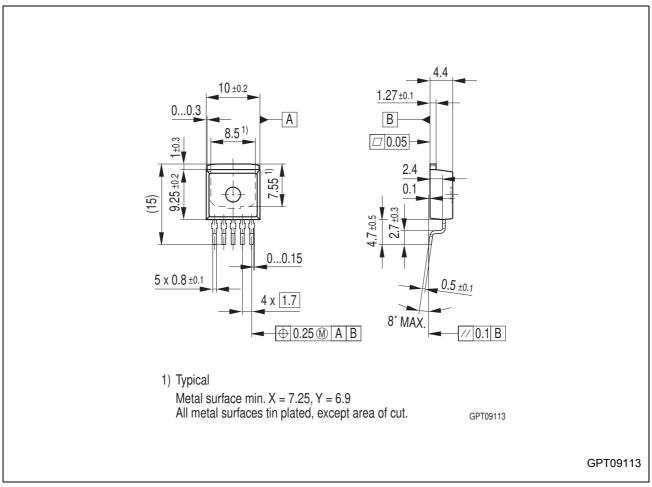


Figure 7 PG-TO263-5-1 (Plastic Transistor Single Outline)

### **Green Product (RoHS compliant)**

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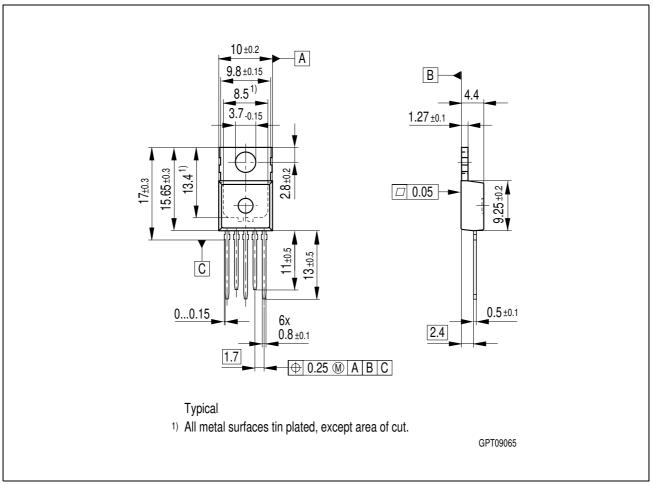


Figure 8 PG-TO220-5-12 (Plastic Transistor Single Outline)

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# TLE 4275

<b>Revision Hist</b>	ory: 2007-02-19	Rev. 1.7					
Previous Version: 1.6							
Page	Page Subjects (major changes since last revision)						
general	Removed all information related to the TLE4275v33 Product Proposal. (See separate datasheet for the TLE4275v33)						
general	Updated Infineon logo						
#1	Added "AEC" and "Green" logo						
#1	Added "Green Product" and "AEC qualified" to the feature list						
#1	Updated Package Names to "PG-xxx"						
general	Removed leadframe variant "P-TO-252-7	1"					
#12 to #15	Added "Green Product" remark						
#17	Disclaimer Update						

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